


Notes: (Unless Otherwise Specified).

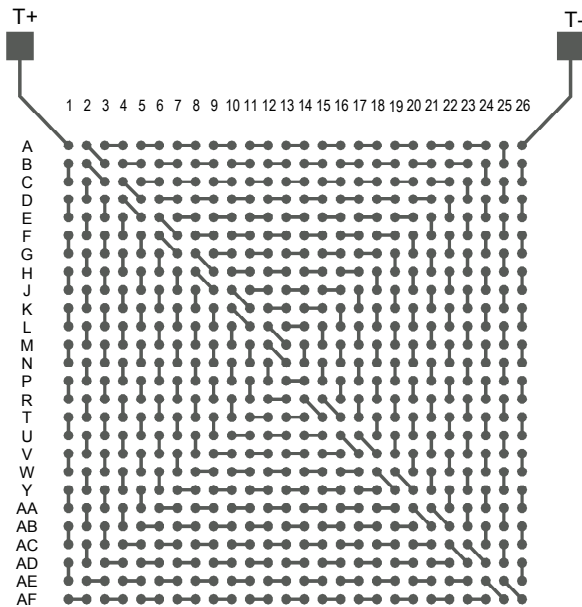
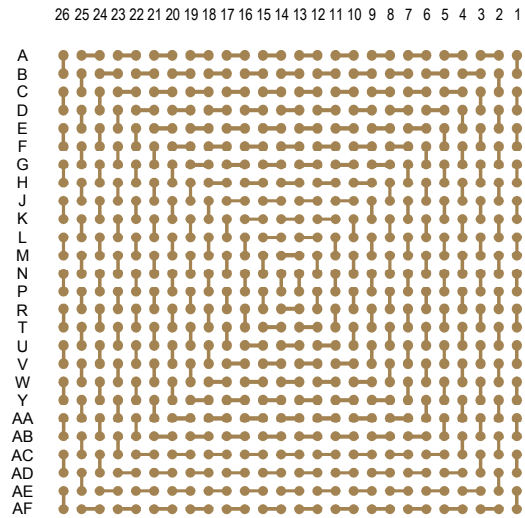
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm [13 MIL].
- 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
LBGA676T.8C-DC269	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	NO
LBGA676T.8C-DC269D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
LBGA676T.8-DC269	Sn63/Pb37	Sn63	NO	NO
LBGA676T.8-DC269D	Sn63/Pb37	Sn63	NO	YES

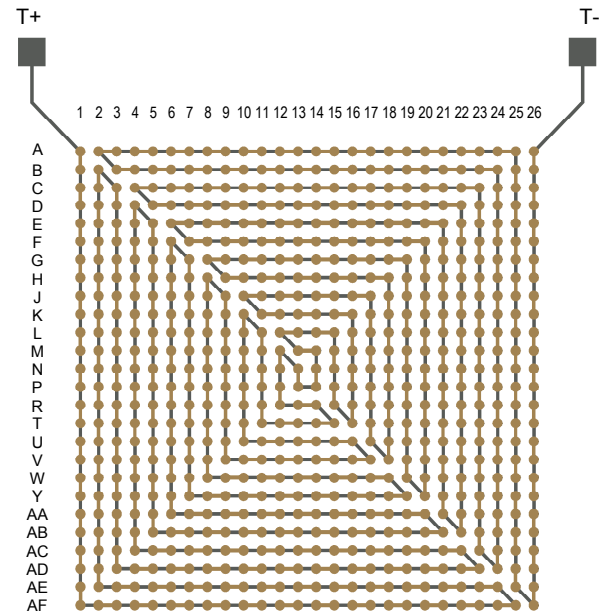
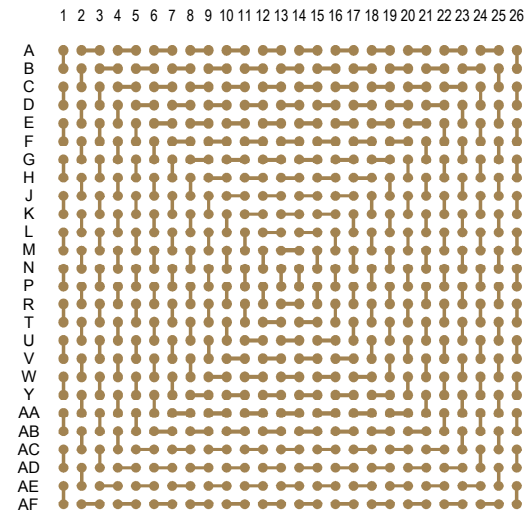
APPROVALS		DATE				
DRAWN	T. Au	03/25/13				
ENG	M. Hart	03/25/13	TITLE		LBGA676T.8-DC269 DAISY CHAIN DUMMY	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			3.5:1	A	582691	A
CUST			DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED						

BALL VIEW



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm [13 MIL].



TITLE			
LBGA67T.8-DC269 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
	A	582691	A
DO NOT SCALE DRAWING			SHEET 2 OF 2